



### Appendix 3 Product End-of-Life Disassembly instructions

#### Product Identification:

<b>Model Name</b>	<b>HP Z5000 Series Digital Entertainment Center</b>
<b>Description</b>	Desktop PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

#### 1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<b>Item Description</b>	<b>Notes</b>	<b>Quantity of items included in product.</b>
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	12
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB / PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants	Declaration limited to case plastics only.	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials		0



containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Clipper	
Screw Driver	
Knife	
Thin slice iron	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1	Top Cover Disassemble: loosing four screws, removing top cover
2	Top Cover mylar Disassemble: using knife to pull Top Cover mylar out of Top Cover
3	Main Bezel sub-assembly Disassemble: ejecting six hooks, pulling out main bezel sub-assembly
4	HDD Bay sub-assembly Disassemble: loosing two screws, taking HDD Bay sub-assembly out of chassis
5	Power Supply Disassemble: loosing five screws, taking Power Supply out of chassis
6	Riser Board sub-assembly Disassemble: loosing three screws, taking Riser Board sub-assembly out of Mother Board sub-assembly
7	Mother Board sub-assembly Disassemble: loosing one screw, pulling Mother Board sub-assembly out of chassis
8	ODD sub-assembly Disassemble: pulling snap up, taking ODD sub-assembly out of chassis
9	Card Reader sub-assembly Disassemble: loosing one screw, taking Card Reader sub-assembly out of chassis
10	Front AV Board sub-assembly Disassemble: loosing one screw, taking Front AV Board out of chassis
11	Display Board Disassemble: loosing four screws, taking Display Board out of chassis
12	Power LED Board Disassemble: loosing two screws, taking Power LED Board out of chassis
13	FAN Holder sub-assembly Disassemble: loosing two screws, taking FAN Holder sub-assembly out of chassis
14	Cable tie Disassemble: pulling two Cable tie out of chassis
15	ODD lock latch Disassemble: pressing four hooks, taking ODD lock latch out of chassis



16	HDD bracket sub-assembly Disassemble: loosening one screw, taking HDD bracket sub-assembly out of chassis
17	Plastic feet Disassemble: loosening two screws, taking two Plastic feet out of chassis
18	Rubber feet Disassemble: loosening two screws, taking two Rubber feet out of chassis
19	Transport Board Disassemble: loosening three screws, taking Transport Board out of Main Bezel
20	Card Reader door sub-assembly Disassemble: pushing Damper hook, taking Card Reader door sub-assembly out of Main Bezel
21	Card Reader door plate, Metal plate and Damper Disassemble: using knife to pull Card Reader plate out of Card Reader door, taking Metal plate and Damper out of Card Reader door
22	MG door sub-assembly Disassemble: pushing Damper hook, taking MG door sub-assembly out of Main Bezel
23	HDD strip and Damper Disassemble: pushing HDD strip right side, taking HDD strip and Damper out of MG door
24	MG door plate and Metal plate Disassemble: using knife to pull MG door plate out of MG door, taking Metal plate out of MG door
25	Front AV door sub-assembly Disassemble: pushing Damper hook, taking Front AV door sub-assembly out of Main Bezel
26	Front AV door plate, Metal plate and Damper Disassemble: using knife to pull Front AV plate out of Front AV door, taking Metal plate and Damper out of Front AV door
27	ODD door sub-assembly Disassemble: pushing ODD door sub-assembly rightward, taking ODD door sub-assembly out of Main Bezel
28	HP Jewel logo Disassemble: using thin slice iron to push HP Jewel logo out
29	ODD door plate, spring and spring pin Disassemble: using knife to pull ODD door plate out of ODD door, taking spring and spring pin out of ODD door
30	Power Button sub-assembly and spring Disassemble: using thin slice to push Power Button hooks to take Power Button sub-assembly and spring out of Main Bezel
31	Power Button plate Disassemble: using knife to pull Power Button plate out of Power Button
32	Bezel plate Disassemble: using knife to pull Bezel plate out of Main Bezel
33	Display Window Disassemble: using knife to pull Display Window out of Main Bezel
34	AV Button Disassemble: pushing hooks to take AV Button out of Main Bezel
35	Bezel strip Disassemble: pushing hooks to take Bezel strip out of Main Bezel
36	Function Button Disassemble: pushing hooks to take six Function Buttons out of Main Bezel
37	ODD Eject Actuator Disassemble: pushing hook to take ODD Eject Actuator out of Main Bezel
38	ODD pad Disassemble: using knife to pull ODD pad out of ODD Eject Actuator



39	Magnet Disassemble: using clipper to pull three Magnet out of Main Bezel
40	HDD Bay door and spring Disassemble: taking away both side of spring, taking HDD Bay door and spring out of HDD Bay
41	HDD Bay connector Disassemble: loosing two screws, taking HDD Bay connector out of HDD Bay
42	Riser Board plate Disassemble: loosing four screws, taking Riser Board plate out of Riser Board bracket
43	Wireless LAN card Disassemble: loosing two screws, taking Wireless LAN card out of Riser Board
44	Wireless LAN card bracket Disassemble: loosing two screws, taking out Wireless LAN card bracket
45	TV card Disassemble: loosing two screws, taking TV card out of Riser Board
46	TV card bracket Disassemble: loosing two screws, taking out TV card bracket
47	Riser Board Disassemble: loosing one screw, taking Riser Board out of Riser Board bracket
48	TV in card Disassemble: loosing two screws, taking TV in card out of Riser Board bracket
49	Component cap Disassemble: pulling Component cap out of Rear AV Board
50	Rear AV Board Disassemble: loosing five screws, taking Rear AV Board out of Mother Board bracket
51	VGA Switch cable Disassemble: loosing two studs, taking VGA Switch cable out of Mother Board bracket
52	Graphic card Disassemble: loosing one screw, taking Graphic card out of Mother Board bracket
53	Graphic card bracket Disassemble: loosing two studs, taking out Graphic card bracket
54	Mother Board Disassemble: loosing eight screws, taking Mother Board out of Mother Board bracket. <b><u>Remove RTC coin cell battery for selective treatment.</u></b>
55	IR Blaster Board Disassemble: loosing two screws, taking IR Blaster Board out of Mother Board bracket
56	Mother Board mylar and Mother Board rubber Disassemble: pulling out Mother Board mylar and Mother Board rubber out of Mother Board bracket
57	ODD slide latch Disassemble: loosing four screws, taking out ODD slide latch
58	Card Reader Disassemble: loosing three screws, taking Card Reader out of Card Reader bracket
59	USB connector Disassemble: pushing four hooks, taking USB connector out of Card Reader bracket
60	Card Reader Bezel Disassemble: pushing six hooks, taking Card Reader Bezel out of Card Reader bracket
61	Card Reader LED lens Disassemble: using clipper to take out Card Reader LED lens



62	Front AV Board Disassemble: loosening three screws, taking Front AV Board out of Front AV Board bracket
63	FAN Disassemble: pressing three hooks, taking FAN out of FAN Holder
64	HDD and HDD screw rubber Disassemble: loosening four screws, taking HDD and HDD screw rubber out of HDD bracket

- 3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

